# **Specification of Thermoelectric Module**

TEC1-28704

# **Description**

The 287 couples, 50 mm × 50 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 70 °C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

### **Features**

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

# **Application**

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

### **Performance Specification Sheet**

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>	
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U <sub>max</sub> (Voltage)	34.4	37.0	Voltage applied to the module at DT <sub>max</sub>	
I <sub>max</sub> (Amps)	4.6	4.6	DC current through the modules at DT <sub>max</sub>	
Q <sub>Cmax</sub> (Watts)	98.3	107	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	5.85	6.15	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

### Geometric Characteristics Dimensions in millimeters

# Positive lead wire (Red) 20AWG, PVC insulated Negative lead wire (Black) 150±3 Cold side:Tc See ordering option See ordering option See ordering option

# **Manufacturing Options**

### A. Solder:

1. T100: BiSn (Melting Point=138°C)

2. T200: CuSn (Melting Point= 227 °C)

### **B. Sealant:**

1. NS: No sealing (Standard)

2. SS: Silicone sealant

3. EPS: Epoxy sealant

4. Customer specify sealing

### C. Ceramics:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)(AlO)

2. Aluminum Nitride (AlN)

### **D. Ceramics Surface Options:**

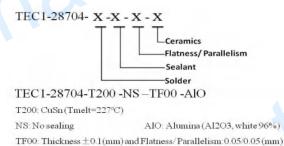
1. Blank ceramics (not metalized)

2. Metalized (Copper-Nickel plating)

# **Ordering Option**

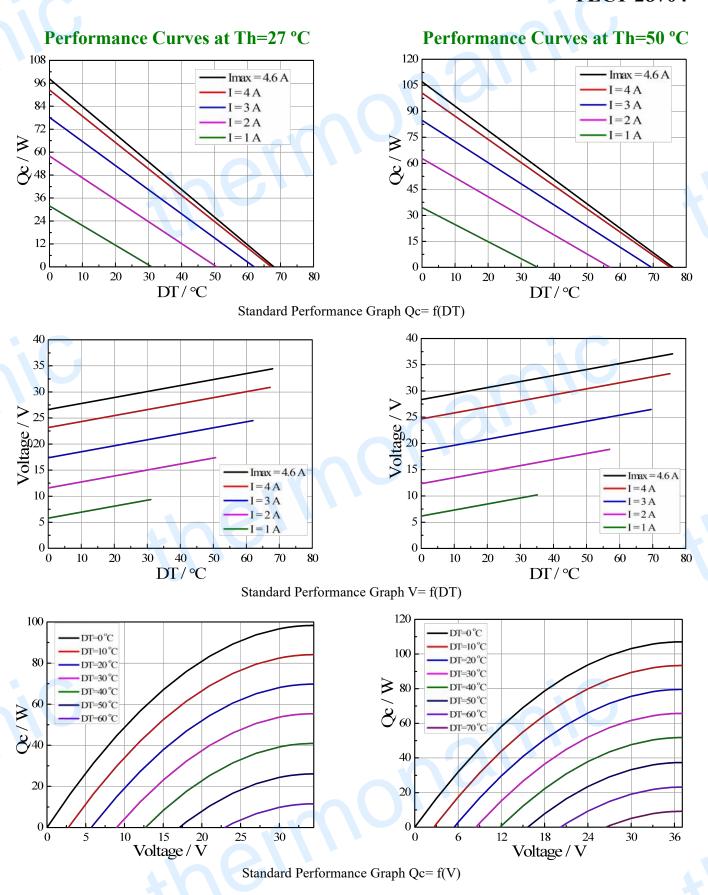
Suffix	Thickness	Flatness/	Lead wire length (mm)		
	H / (mm)	Parallelism (mm)	Standard/Optional length		
TF	0:4.9±0.1	0:0.05/0.05	150±3/Specify		
TF	1:4.9±0.05	1:0.025/0.025	150±3/Specify		
Eg. TF00: Thickness 4.9±0.1 (mm) and Flatness 0.05/0.05(mm)					

# Naming for the Module



# **Specification of Thermoelectric Module**

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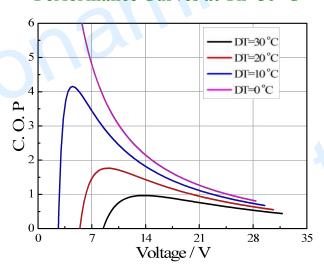
### **TEC1-28704**

### Performance Curves at Th=27 °C

# 5 4 DI=30°C DI=20°C DI=10°C DI=0°C

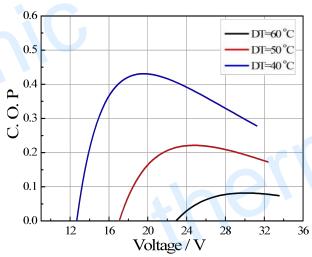
Voltage / V

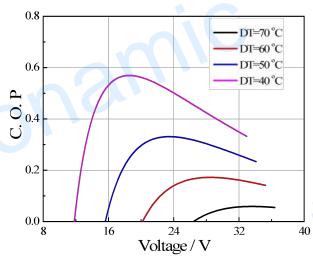
### Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C

35





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

# **Operation Cautions**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC